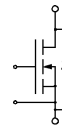


SEMITRANS® M Power MOSFET Modules SKM 181



SEMITRANS M1



Features

- N Channel, enhancement mode
- Short internal connections avoid oscillations
- Switching kW's in less than 1 μ s
- Isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearances and creepage distances
- UL recognized, file no. E 63 532

Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- DC choppers
- Resonant and welding inverters
- AC motor drives
- Laser power supplies
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.

Absolute Maximum Ratings			
Symbol	Conditions ¹⁾	Values	Units
V _{DS}	R _{GS} = 20 kΩ	800	V
V _{DGR}		800	V
I _D		36	A
I _{DM}		144	A
V _{GS}		± 20	V
P _D	AC, 1 min	700	W
T _J , T _{stg}		− 55 . . . +150	°C
V _{isol}		2 500	V
humidity		Class F	
climate		DIN 40 040 DIN IEC 68 T.1	55/150/56
Inverse Diode			
I _F = − I _D		36	A
I _{FM} = − I _{DM}		144	A

Characteristics					
Symbol	Conditions ¹⁾	min.	typ.	max.	Units
V _{(BR)DSS}	V _{GS} = 0, I _D = 0,25 mA	800	—	—	V
V _{GS(th)}	V _{GS} = V _{DS} , I _D = 1 mA	2,1	3,0	4,0	V
I _{DSS}	V _{GS} = 0, $\left. \begin{array}{l} T_J = 25\text{ }^{\circ}\text{C} \\ V_{DS} = 800\text{ V} \end{array} \right\} T_J = 125\text{ }^{\circ}\text{C}$	—	50	250	μA
I _{GSS}	V _{GS} = 20 V, V _{DS} = 0	—	300	1000	μA
R _{DS(on)}	V _{GS} = 10 V, I _D = 23 A	—	10	100	mΩ
g _{fs}	V _{GS} = 25 V, I _D = 23 A	15	25	—	S
C _{CHC}	$\left. \begin{array}{l} V_{GS} = 0 \\ V_{DS} = 25\text{ V} \\ f = 1\text{ MHz} \end{array} \right\}$	—	—	160	pF
C _{iSS}		—	24	32	nF
C _{oss}		—	1,3	2	nF
C _{rSS}		—	0,5	0,8	nF
L _{DS}		—	—	20	nH
t _{d(on)}	$\left. \begin{array}{l} V_{DD} = 400\text{ V} \\ I_D = 23\text{ A} \end{array} \right\}$	—	60	—	ns
t _r		—	30	—	ns
t _{d(off)}	$\left. \begin{array}{l} V_{GS} = 10\text{ V} \\ R_{GS} = 3,3\text{ }\Omega \end{array} \right\}$	—	270	—	ns
t _f		—	70	—	ns
Inverse Diode					
V _{SD}	I _F = 72 A, V _{GS} = 0	—	1,1	1,4	V
t _{rr}	T _J = 25 °C ²⁾	—	1200	—	ns
	T _J = 150 °C ²⁾	—	—	—	ns
Q _{rr}	T _J = 25 °C ²⁾	—	42	—	μC
	T _J = 150 °C ²⁾	—	50	—	μC
Thermal Characteristics					
R _{thjc}	M ₁ , surface 10 μm	—	—	0,18	°C/W
R _{thch}		—	—	0,05	°C/W

Mechanical Data		4	—	5	Nm
Symbol	Conditions				
M ₁	to heatsink, SI Units	35	—	44	lb.in.
M ₂	for terminals, SI Units	2,5	—	3,5	Nm
	for terminals, US Units	22	—	24	lb.in.
a		—	—	5x9,81	m/s ²
w		—	—	150	g
Case	→ page B 5 – 2	D 15			

¹⁾ T_{case} = 25 °C, unless otherwise specified.

²⁾ I_F = - I_D, V_R = 100 V, - di_F/dt = 100 A/ μ s

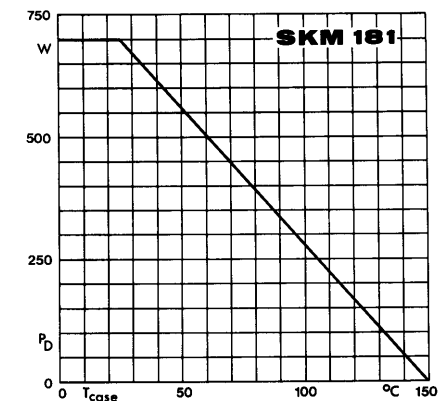


Fig. 1 Rated power dissipation vs. temperature

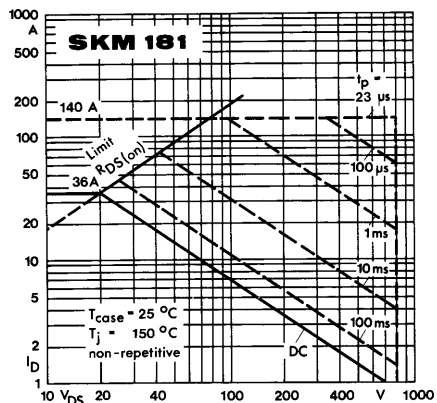


Fig. 2 Maximum safe operating area

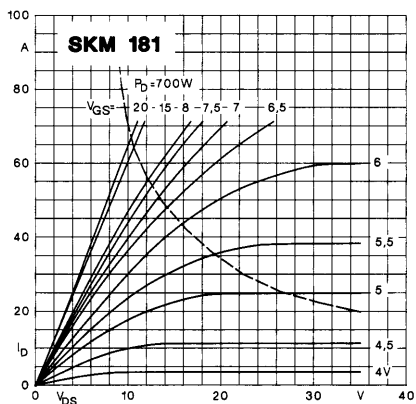


Fig. 3 Output characteristic

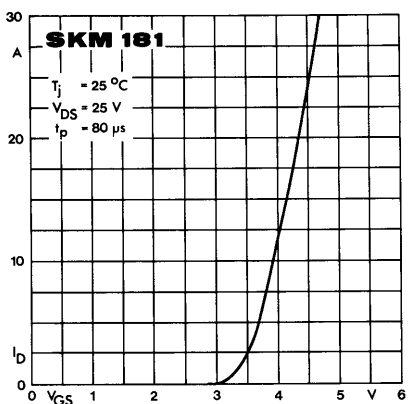


Fig. 4 Transfer characteristic

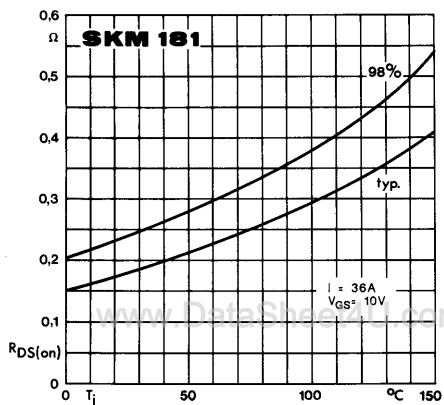


Fig. 5 On-resistance vs. temperature

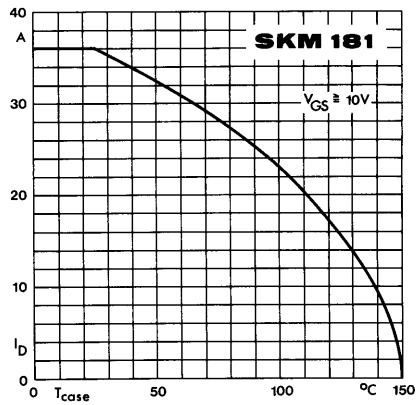


Fig. 6 Rated current vs. temperature

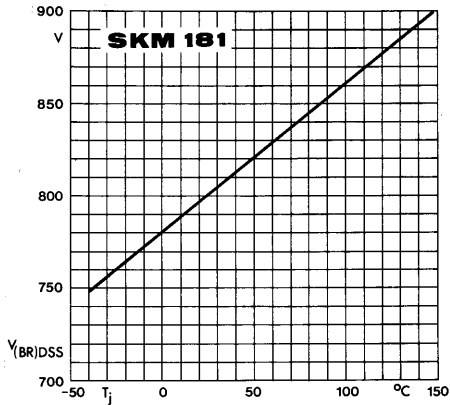


Fig. 7 Breakdown voltage vs. temperature

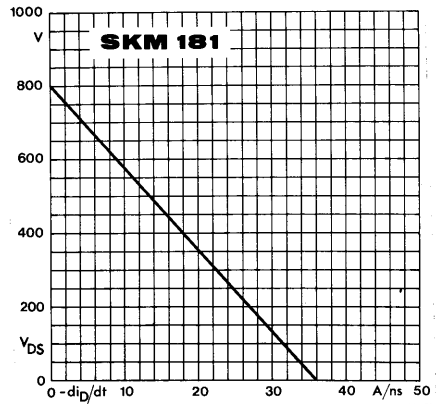


Fig. 8 Drain-source voltage derating

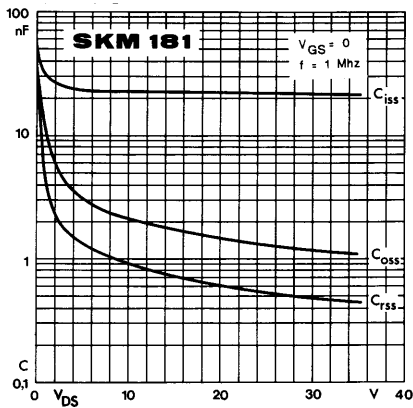


Fig. 9 Capacitances vs. drain-source voltage

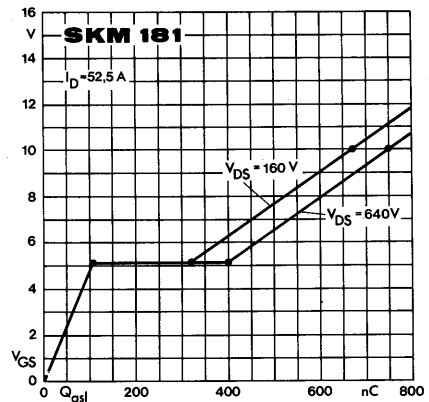


Fig. 10 Gate charge characteristic

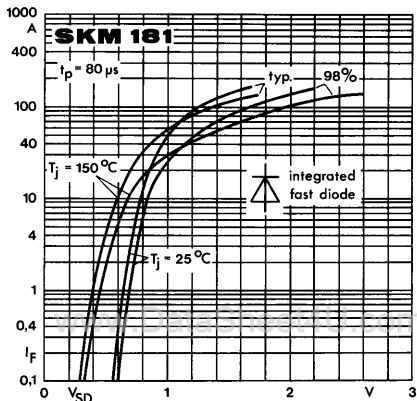


Fig. 11. Diode forward characteristic

